

REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20150109	2015.01.26	Michelle
A3	Release To ECN20150705	2015.07.17	Michelle
A4	Release To ECN20150805	2015.08.06	Michelle

RoHS Compliant

Specification

- 1.Current Rating:0.5A AC/DC(AWG32) 0.2A AC/DC(AWG36)
- 2.Voltage Rating:30V AC
- 3.Contact Resistance:20mΩ Max.(Initial) 40mΩ Max.(Final)
- 4.Insulation Resistance:100MΩ Min. At DC 200V
- 5.Dielectric Withstanding Voltage:AC200V/Minute
- 6.Operating Temperature:-25°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.20mm
- 3.Contact Pin:Copper Alloy T=0.15mm

Finish:

- 1.Housing:Natural
- 2.Tab:Tin Plated Over Nickel
- 3.Contact Pin:See P/N Option

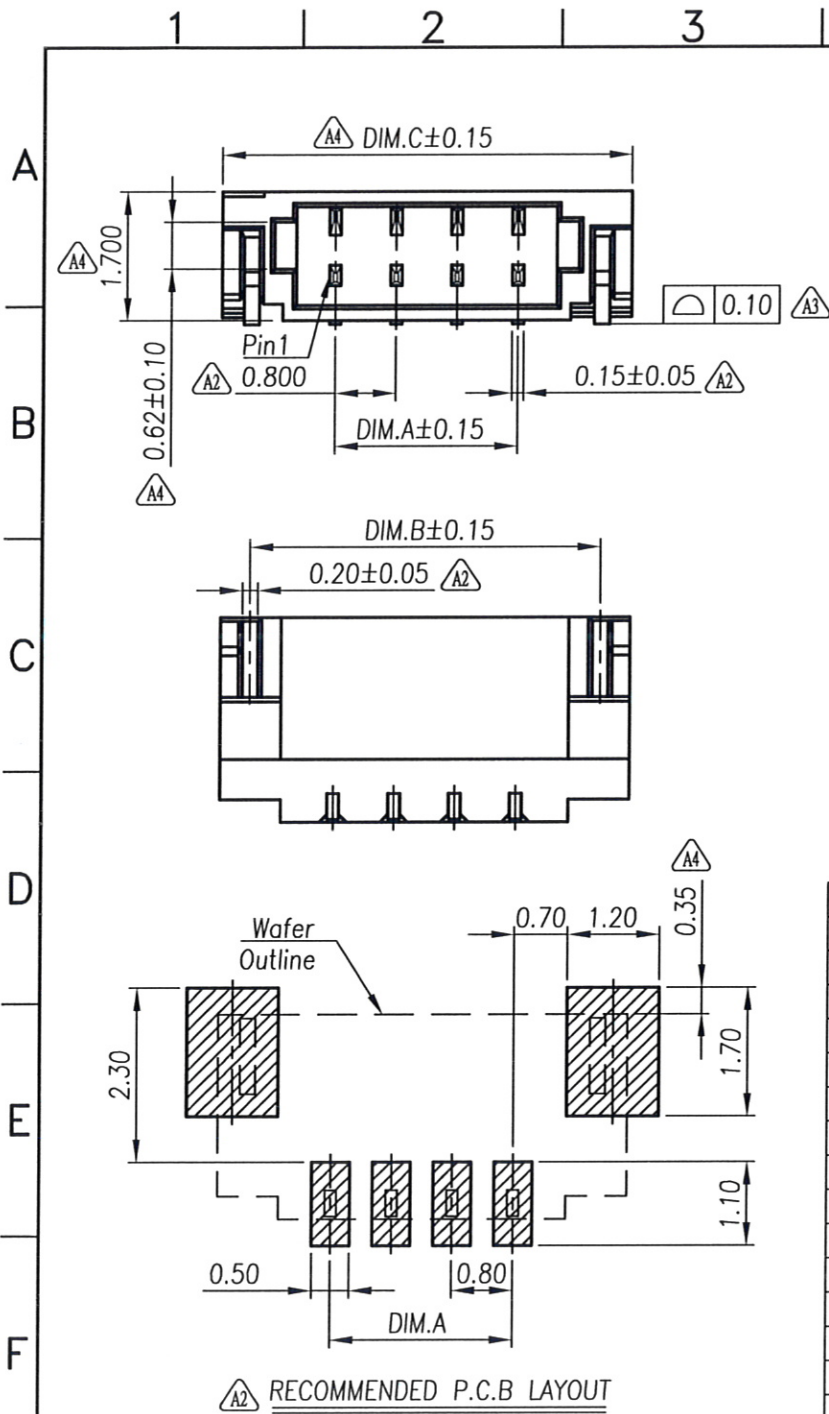
Part No.:AS09601 XX K X X 1


No. Of Pin: 02~20
Packing: 1:T&R, 4:Tube

△A2 Housing Material K:HTN UL94V-0 Natural H.F
△A2 Plating 2:Matte Tin Plated Over Nickel, 3:Gold Plated Over Nickel




PIN	DIM.A	DIM.B	DIM.C
02	0.80	3.00	3.80
03	1.60	3.80	4.60
04	2.40	4.60	5.40
05	3.20	5.40	6.20
06	4.00	6.20	7.00
07	4.80	7.00	7.80
08	5.60	7.80	8.60
09	6.40	8.60	9.40
10	7.20	9.40	10.20
12	8.80	11.00	11.80
14	10.40	12.60	13.40
15	11.20	13.40	14.20
16	12.00	14.20	15.00
17	12.80	15.00	15.80
20	15.20	17.40	18.20






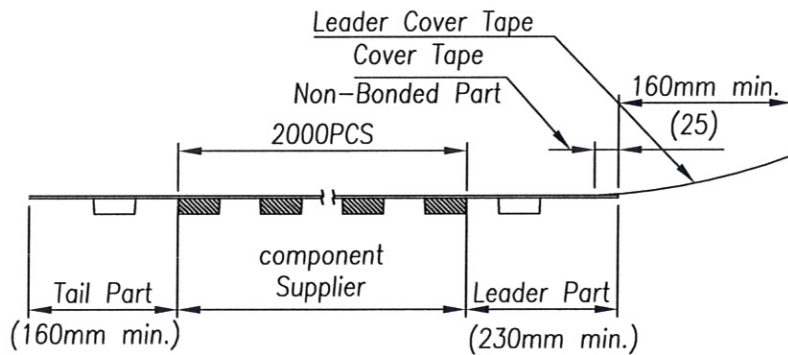
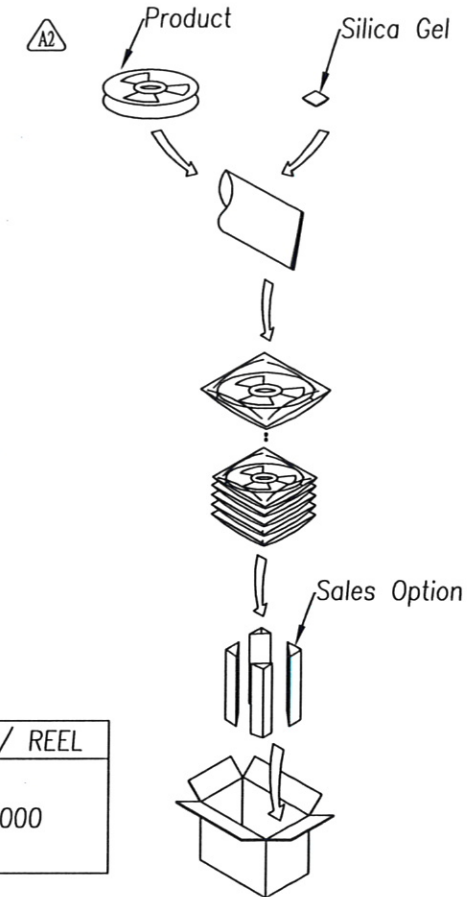
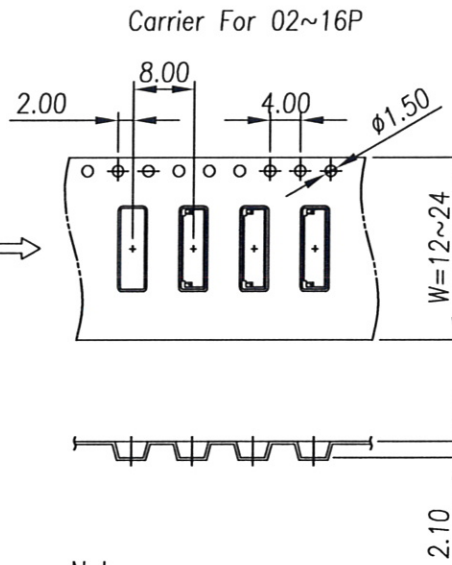
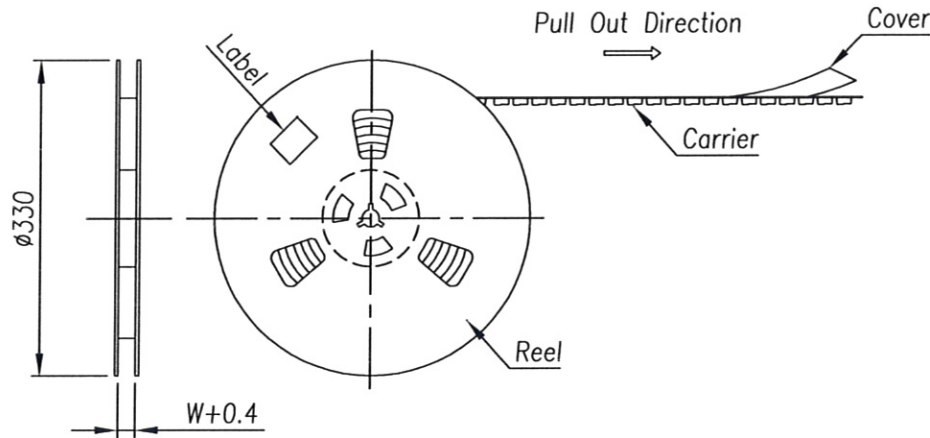
金上達科技股份有限公司

GOLDENSUND TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 0.80mm 90° SMT Single Row	
.x± 0.35	x.± 2'	APR. C.F.Liao 20150806	PART NO. AS09601XXKXX1	DWG NO. AS09601XXKXX1
.xx± 0.25	.x± 1'	CHK. Abel 20150806	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx± 0.5'	DRW. Michelle 20150806	SIZE: A4	SCALE 10:1
		SHEET 1 / 2		REV A4

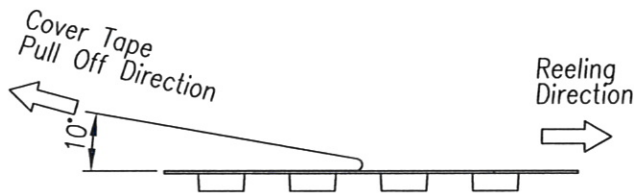
RoHS Compliant 


REV	MODIFICATION	DATE	DRAW
A2	Release To ECN20150109	2015.01.26	Michelle
A3	Release To ECN20150705	2015.07.17	Michelle
A4	Release To ECN20150805	2015.08.06	Michelle



- Notes:
1. Material : PS
 2. Part No.: AS09601XXKX11


PIN NO.	W ±0.30	PCS / REEL
02.03	12	2000
04.05.06	16	
08.10.16	24	





金上達科技股份有限公司

GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 0.80mm 90° SMT Single Row	
.x± 0.35	x.*± 2'	APR. C.F.Liao 20150806	PART NO. AS09601XXKXX1	DWG NO. AS09601XXKXX1
.xx± 0.25	.x.*± 1'	CHK. Abel 20150806	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx.*± 0.5'	DRA. Michelle 20150806	SIZE: A4	
		SHEET 2 / 2		REV A4